



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CJ03 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ068B
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CJ0388A11N1

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings

REVIEWED : Eisley APPROVED : Sun VERIFIED : Jessie .

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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5 A 150 V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max. EIA-364-23B	Less than 50 mΩ (Initial) Less than 80 mΩ (Final)
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal EIA-364-20B	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground EIA-364-21C	More than 500 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Durability	1000 Cycles operating at a rate of 500±50 cycles per hour, without load. EIA-364-09C	Appearance: No damage Contact resistance: Less than 80 mΩ (Final)
8.2	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed EIA-364-13B	3.06 Kgf (30 N) Max.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions EIA-364-28D	There shall be no less in continuity longer than 1μs. Appearance: No damage
9.2	Shock	No. of Drops: 3 drops each to normal and reversed directions of X , Y and Z axes, totally 18 drops, passing DC 1mA current during the test. Waveform: Half-sine shock plus. Accelerate Velocity :50G. Pulse duration: 11ms. EIA-364-27B	There shall be no less in continuity longer than 1μs. Appearance: No damage

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	ITEM	TEST CONDITION	REQUIREMENT
9.3	Heat aging	70 ± 2 °C , 96 hours EIA-364-17B	Appearance: No damage Contact resistance: Less than 80 mΩ (Final)
9.4	Humidity test	At a temperature of 40±2 °C and relative humidity of 90-95% RH for 96 hours. EIA-364-31B	Appearance: No damage Contact resistance: Less than 80 mΩ (Final)
9.5	Salt spray	Temperature: 35 ± 3 °C Solution: 5 ± 1% Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial
9.6	Solder ability	Soldering time: 5±1.0 second Soldering pot: 245± 5 °C EIA-364-52B	Minimum: 95% of immersed area
9.7	Resistance to soldering heat	Recommend Wave Soldering Profile (11.) EIA-364-56C	Appearance: No damage

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10. STORAGE & OPERATING TEMPERATURE RANGE: -40 to + 85°C

11. Wave Solder Profile

Note:
The measuring point for the specified temperature shall be on the soldered part of the leads.

